

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1 - 6 (Canceled)

Claim 7 (Currently Amended)

A substrate processing apparatus comprising:

substrate retaining means for retaining a substrate;

first processing solution supply means for supplying a first processing solution to the substrate retained by said substrate retaining means thereby subjecting the substrate to a predetermined wet process;

second processing solution supply means for supplying a rinse liquid as a second processing solution to the substrate retained by said substrate retaining means thereby subjecting the substrate to a rinsing process for removing said first processing solution; and

anti-drying solution supply means for supplying an anti-drying solution having a composition which is different from that of said rinse liquid to said substrate subjected to said rinsing process, thereby replacing said rinse liquid adhered to said substrate with said anti-drying solution.

Claim 8 (Previously Presented)

The substrate processing apparatus according to claim 7, wherein said anti-drying solution supply means supplies, as said anti-drying solution, a replacing solution having a higher affinity with a high pressure fluid than said rinse liquid.

Claim 9 (Currently Amended)

A substrate processing apparatus comprising:

substrate retaining means for retaining a substrate wet with a rinse liquid; and

anti-drying solution supply means for supplying an anti-drying solution having a composition which is different from that of said rinse liquid to the substrate retained by said substrate retaining means, thereby replacing said rinse liquid adhered to said substrate with said anti-drying solution.

Claim 10 (Previously Presented)

The substrate processing apparatus according to claim 9, wherein said anti-drying solution supply means supplies, as said anti-drying solution, a replacing solution having a higher affinity with a high-pressure fluid than said rinse liquid.

Claim 11 (Original)

A substrate processing system comprising:

a wet processing unit having the same construction as the substrate processing apparatus according to claim 7;

a high-pressure drying unit for high-pressure drying said substrate by the use of a high-pressure fluid or a mixture of the high-pressure fluid and a chemical agent, as a processing fluid; and

a transport unit for transporting said substrate, as wetted with said anti-drying solution, from said wet processing unit to said high-pressure drying unit.

Claim 12 (Previously Presented)

The substrate processing system according to claim 11, wherein a replacing solution having a higher affinity with said high-pressure fluid than said rinse liquid is used as said anti-drying solution.

Claim 13 (Original)

The substrate processing system according to claim 11, wherein said transport unit wet-transportes said substrate between said units, said substrate being accommodated in a transport container.

Claim 14 (Previously Presented)

A substrate processing system comprising:

a wet processing unit for supplying a rinse liquid to a substrate thereby subjecting the substrate to a rinsing process;

a replacing unit having the same construction as the substrate processing apparatus according to claim 9;

a high-pressure drying unit for high-pressure drying the substrate delivered from said replacing unit by the use of a high-pressure fluid or a mixture of the high-pressure fluid and a chemical agent, as a processing fluid; and

a transport unit for transporting said substrate, as wetted with said rinse liquid, from said wet processing unit to said replacing unit, and for transporting said substrate, as wetted with said anti-drying solution, from said replacing unit to said high-pressure drying unit.

Claim 15 (Previously Presented)

The substrate processing system according to claim 14, wherein a replacing solution having a higher affinity with said high-pressure fluid than said rinse liquid is used as said anti-drying solution.

Claim 16 (Original)

The substrate processing system according to claim 14, wherein said transport unit wet-transport said substrate between said units, said substrate being accommodated in a transport container.

Claim 17 (Currently Amended)

A substrate processing apparatus comprising:

a plurality of developing units for performing different developing processes for a substrate, respectively;

a high-pressure processing unit for allowing a high-pressure fluid or a mixture of the high-pressure fluid and a chemical agent, as a processing fluid, to contact a surface of said

developed substrate thereby performing a predetermined surface treatment for said developed substrate; and

a transport unit, capable of accessing said plural developing units and said high-pressure processing unit, for unloading the developed substrate from any one of said plural developing units and for loading said developed substrate into said high-pressure processing unit,

wherein each of said plural developing units includes:

developing solution supply means for supplying a developing solution to said substrate;

rinse liquid supply means for supplying a rinse liquid to said substrate; and

replacing solution supply means for supplying a replacing solution having a composition which is different from that of said rinse liquid to said substrate thereby replacing said rinse liquid with said replacing solution.

Claim 18 (Original)

The substrate processing apparatus according to claim 17, wherein said transport unit wet-transportes said developed substrate from any one of said plural developing units to said high-pressure processing unit.

Claim 19 (Original)

The substrate processing apparatus according to claim 17, comprising a plural number of said high-pressure processing units,

wherein said transport unit is capable of accessing said plural high-pressure processing units for unloading said developed substrate from any one of said plural developing units and for loading said developed substrate selectively to one of said plural high-pressure processing units.

Claim 20 (Currently Amended)

The substrate processing apparatus according to claim 17, wherein said plural developing units each perform a replacing process as a final processing of said developing process for replacing the solution component adhered to said substrate with a said replacing solution common to said plural developing units.

Claim 21 (Currently Amended)

A substrate processing apparatus comprising:

a plurality of developing units for performing different developing processes for on a substrate, respectively;

a replacing unit for replacing a solution component adhered to said developed substrate with a replacing solution;

a high-pressure processing unit for allowing a high-pressure fluid or a mixture of a high-pressure fluid and a chemical agent, as a processing fluid, to contact a surface of said substrate subjected to the replacing process thereby performing a predetermined surface treatment for said substrate subjected to the replacing process; and

a transport unit, capable of accessing said plural developing units, said replacing unit and said high-pressure processing unit, for unloading the developed substrate from any one of said plural developing units and for loading said developed substrate into said replacing unit and for unloading the substrate subjected to the replacing process from said replacing unit and for loading said substrate subjected to the replacing process into said high-pressure processing unit,

wherein each of said plural developing units includes:

developing solution supply means for supplying a developing solution to said substrate;
and

rinse liquid supply means for supplying a rinse liquid to said substrate,

wherein said replacing solution has a composition which is different from that of said rinse liquid.

Claim 22 (Previously Presented)

The substrate processing apparatus according to claim 21, wherein said transport unit wet-transportes said substrate among said plural developing units, said replacing unit and said high-pressure processing unit.

Claim 23 (Previously Presented)

The substrate processing apparatus according to claim 21, comprising a plural number of said high-pressure processing units,

wherein said transport unit is capable of accessing said plural high-pressure processing units for unloading said substrate subjected to the replacing process from said replacing unit and for loading said substrate selectively to one of said plural high-pressure processing units.

Claim 24 (Currently Amended)

The substrate processing apparatus according to claim 21, wherein said replacing unit performs a replacing process for replacing the solution component adhered to said substrate with a common said replacing solution common to said plural developing units.

Claim 25 (Previously Presented)

The substrate processing apparatus according to claim 7, wherein said first processing solution supply means supplies, as said first processing solution, a developing solution to the substrate for developing.

Claim 26 (New)

The substrate processing system according to claim 11, wherein said anti-drying solution is liquid for preventing said substrate from becoming air-dry during the transportation of the substrate from said wet processing unit to said high-pressure drying unit.

Claim 27 (New)

The substrate processing system according to claim 14, wherein said anti-drying solution is liquid for preventing said substrate from becoming air-dry during the transportation of the substrate from said replacing unit to said high-pressure drying unit.

Claim 28 (New)

The substrate processing apparatus according to claim 17, wherein said replacing solution is liquid for preventing said substrate from becoming air-dry during the transportation of the substrate from any one of said plural developing units to said high-pressure processing unit.

Claim 29 (New)

The substrate processing apparatus according to claim 21, wherein said replacing solution is liquid for preventing said substrate from becoming air-dry during the transportation of the substrate from said replacing unit to said high pressure processing unit.